Embedded Module

Open Standard Module™ - iesy AM335x OSM-LF

Technical Concept

TI Sitara AM 3354 Processor:

1GB RAM:

► Flash-Memory: 32GB eMMC

Dimension: 45 mm x 45 mm

Footprint: OSM Size-L

Land Grid Array (LGA) with 662 contacts

► Power-Supply: 5V via LGA Kontakte

Linux based BSP (Yocto) ➤ Software:

Temperature:

> Operating: -40 °C to +85 °C > Storage: -40 °C to +85 °C

- Features & Interfaces
 - > 2x Ethernet
 - > 2x USB 2.0
 - > 4x UART
 - > 8x GPIO

 - > 1x SPI
 - > 2x I2C
 - > 1x I2S
 - > 1x SDIO
 - > 1x CAN
 - > 1x JTAG
 - > 2x PWM
 - > 1x Display (RGB)



About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of flexibility, scalability, but also costs. OSM™ solder-down modules can be individually adapted to the respective customer requirements. For this purpose, the individual modules can be made available to the SMT process by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.



iesy.com/osm